

AMENDMENT UNDER 37 C.F.R. § 1.116  
EXPEDITED PROCEDURE  
GROUP 2894  
**PATENT APPLICATION**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of	Docket No: Q78432
Hien Boon TAN, et al.	
Appln. No.: 10/721,382	Group Art Unit: 2894
Confirmation No.: 6007	Examiner: David E. Graybill
Filed: November 26, 2003	
For: HIGH PERFORMANCE CHIP SCALE LEADFRAME PACKAGE METHOD OF MANUFACTURING	

**AMENDMENT UNDER 37 C.F.R. § 1.116**

**MAIL STOP AF**  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In response to the Office Action dated October 10, 2008, please amend the above-identified application as follows on the accompanying pages.

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